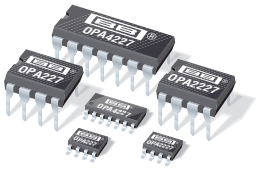
Burr-Brown Products
from Texas Instruments



OPA227
OPA2227
OPA4227
OPA228
OPA2228
OPA4228

SBOS110A – MAY 1998 – REVISED JANUARY 2005

High Precision, Low Noise OPERATIONAL AMPLIFIERS

FEATURES

- LOW NOISE: 3nV/√Hz
- WIDE BANDWIDTH:
  OPA227: 8MHz, 2.3V/μs
  OPA228: 33MHz, 10V/μs
- SETTLING TIME: 5μs
  (significant improvement over OP-27)
- HIGH CMRR: 138dB
- HIGH OPEN-LOOP GAIN: 160dB
- LOW INPUT BIAS CURRENT: 10nA max
- LOW OFFSET VOLTAGE: 75μV max
- WIDE SUPPLY RANGE: ±2.5V to ±18V
- OPA227 REPLACES OP-27, LT1007, MAX427
- OPA228 REPLACES OP-37, LT1037, MAX437
- SINGLE, DUAL, AND QUAD VERSIONS

APPLICATIONS

- DATA ACQUISITION
- TELECOM EQUIPMENT
- GEOPHYSICAL ANALYSIS
- VIBRATION ANALYSIS
- SPECTRAL ANALYSIS
- PROFESSIONAL AUDIO EQUIPMENT
- ACTIVE FILTERS
- POWER SUPPLY CONTROL

SPICE model available for OPA227 at www.ti.com

DESCRIPTION

The OPA227 and OPA228 series op amps combine low noise and wide bandwidth with high precision to make them the ideal choice for applications requiring both ac and precision dc performance.

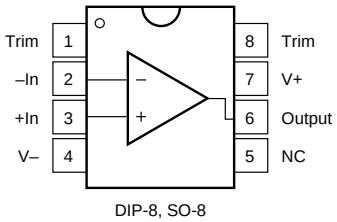
The OPA227 is unity-gain stable and features high slew rate (2.3V/μs) and wide bandwidth (8MHz). The OPA228 is optimized for closed-loop gains of 5 or greater, and offers higher speed with a slew rate of 10V/μs and a bandwidth of 33MHz.

The OPA227 and OPA228 series op amps are ideal for professional audio equipment. In addition, low quiescent current and low cost make them ideal for portable applications requiring high precision.

The OPA227 and OPA228 series op amps are pin-for-pin replacements for the industry standard OP-27 and OP-37 with substantial improvements across the board. The dual and quad versions are available for space savings and per-channel cost reduction.

The OPA227, OPA228, OPA2227, and OPA2228 are available in DIP-8 and SO-8 packages. The OPA4227 and OPA4228 are available in DIP-14 and SO-14 packages with standard pin configurations. Operation is specified from –40°C to +85°C.

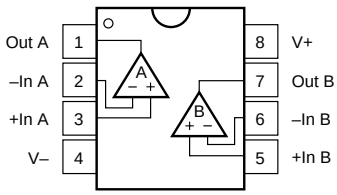
OPA227, OPA228



DIP-8, SO-8

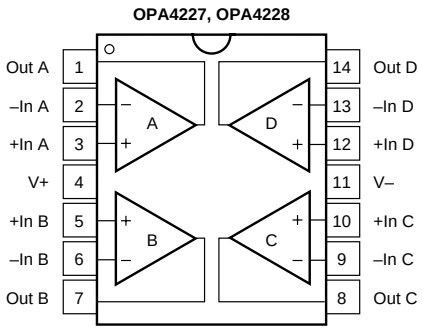
NC = Not Connected

OPA2227, OPA2228



DIP-8, SO-8

OPA4227, OPA4228



DIP-14, SO-14

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

Copyright © 1998-2005, Texas Instruments Incorporated

SPECIFICATIONS: V_S = ±5V to ±15V

OPA227 Series

At T_A = +25°C, and R_L = 10kΩ, unless otherwise noted.
Boldface limits apply over the specified temperature range, T_A = –40°C to +85°C.

PARAMETER	CONDITION	OPA227P, U OPA2227P, U			OPA227PA, UA OPA2227PA, UA OPA4227PA, UA			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
OFFSET VOLTAGE								
Input Offset Voltage V_{OS}			±5	±75		±10	±200	µV
T_A = –40°C to +85°C				**±100**			**±200**	µV
vs Temperature dV_{OS}/dT			**±0.1**	**±0.6**		**±0.3**	**±2**	µV/°C
vs Power Supply PSRR	V_S = ±2.5V to ±18V		±0.5	±2		*	*	µV/V
T_A = –40°C to +85°C				**±2**			*	µV/V
vs Time			0.2			*		µV/mo
Channel Separation (dual, quad)	dc		0.2			*		µV/V
	f = 1kHz, R_L = 5kΩ		110			*		dB
INPUT BIAS CURRENT								
Input Bias Current I_B			±2.5	±10		*	*	nA
T_A = –40°C to +85°C				**±10**			*	nA
Input Offset Current I_{OS}			±2.5	±10		*	*	nA
T_A = –40°C to +85°C				**±10**			*	nA
NOISE								
Input Voltage Noise, f = 0.1Hz to 10Hz			90			*		nVp-p
			15			*		nVrms
Input Voltage Noise Density, f = 10Hz e_n			3.5			*		nV/√Hz
f = 100Hz			3			*		nV/√Hz
f = 1kHz			3			*		nV/√Hz
Current Noise Density, f = 1kHz i_n			0.4			*		pA/√Hz
INPUT VOLTAGE RANGE								
Common-Mode Voltage Range V_{CM}		(V–)+2		(V+)–2	*		*	V
Common-Mode Rejection CMRR	V_{CM} = (V–)+2V to (V+)–2V	120	138		*	*		dB
T_A = –40°C to +85°C		**120**			*			dB
INPUT IMPEDANCE								
Differential			10^7 || 12			*		Ω || pF
Common-Mode	V_{CM} = (V–)+2V to (V+)–2V		10^9 || 3			*		Ω || pF
OPEN-LOOP GAIN								
Open-Loop Voltage Gain A_{OL}	V_O = (V–)+2V to (V+)–2V, R_L = 10kΩ	132	160		*	*		dB
T_A = –40°C to +85°C		**132**			*			dB
	V_O = (V–)+3.5V to (V+)–3.5V, R_L = 600Ω	132	160		*	*		dB
T_A = –40°C to +85°C		**132**			*			dB
FREQUENCY RESPONSE								
Gain Bandwidth Product GBW			8			*		MHz
Slew Rate SR			2.3			*		V/µs
Settling Time: 0.1%	G = 1, 10V Step, C_L = 100pF		5			*		µs
0.01%	G = 1, 10V Step, C_L = 100pF		5.6			*		µs
Overload Recovery Time	V_{IN} • G = V_S		1.3			*		µs
Total Harmonic Distortion + Noise THD+N	f = 1kHz, G = 1, V_O = 3.5Vrms		0.00005			*		%
OUTPUT								
Voltage Output	R_L = 10kΩ	(V–)+2		(V+)–2	*		*	V
T_A = –40°C to +85°C	R_L = 10kΩ	**(V–)+2**		**(V+)–2**	*		*	V
	R_L = 600Ω	(V–)+3.5		(V+)–3.5	*		*	V
T_A = –40°C to +85°C	R_L = 600Ω	**(V–)+3.5**		**(V+)–3.5**	*		*	V
Short-Circuit Current I_{SC}			±45			*		mA
Capacitive Load Drive C_{LOAD}			See Typical Curve			*		
POWER SUPPLY								
Specified Voltage Range V_S		±5		±15	*		*	V
Operating Voltage Range		±2.5		±18	*		*	V
Quiescent Current (per amplifier) I_Q	I_O = 0		±3.7	±3.8		*	*	mA
T_A = –40°C to +85°C	I_O = 0			**±4.2**			*	mA
TEMPERATURE RANGE								
Specified Range		–40		+85	*		*	°C
Operating Range		–55		+125	*		*	°C
Storage Range		–65		+150	*		*	°C
Thermal Resistance θ_{JA}								
SO-8 Surface Mount			150			*		°C/W
DIP-8			100			*		°C/W
DIP-14			80			*		°C/W
SO-14 Surface Mount			100			*		°C/W

* Specifications same as OPA227P, U.

SPECIFICATIONS: V_S = ±5V to ±15V

OPA228 Series

At T_A = +25°C, and R_L = 10kΩ, unless otherwise noted.
Boldface limits apply over the specified temperature range, T_A = –40°C to +85°C.

PARAMETER	CONDITION	OPA228P, U OPA2228P, U			OPA228PA, UA OPA2228PA, UA OPA4228PA, UA			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
OFFSET VOLTAGE								
Input Offset Voltage V_{OS}			±5	±75		±10	±200	µV
T_A = –40°C to +85°C				**±100**			**±200**	µV
vs Temperature dV_{OS}/dT			**±0.1**	**±0.6**		**±0.3**	**±2**	µV/°C
vs Power Supply PSRR	V_S = ±2.5V to ±18V		±0.5	±2		*	*	µV/V
T_A = –40°C to +85°C				**±2**			*	µV/V
vs Time			0.2			*		µV/mo
Channel Separation (dual, quad)	dc		0.2			*		µV/V
	f = 1kHz, R_L = 5kΩ		110			*		dB
INPUT BIAS CURRENT								
Input Bias Current I_B			±2.5	±10		*	*	nA
T_A = –40°C to +85°C				**±10**			*	nA
Input Offset Current I_{OS}			±2.5	±10		*	*	nA
T_A = –40°C to +85°C				**±10**			*	nA
NOISE								
Input Voltage Noise, f = 0.1Hz to 10Hz			90			*		nVp-p
			15			*		nVrms
Input Voltage Noise Density, f = 10Hz e_n			3.5			*		nV/√Hz
f = 100Hz			3			*		nV/√Hz
f = 1kHz			3			*		nV/√Hz
Current Noise Density, f = 1kHz i_n			0.4			*		pA/√Hz
INPUT VOLTAGE RANGE								
Common-Mode Voltage Range V_{CM}		(V–)+2		(V+)–2	*		*	V
Common-Mode Rejection CMRR	V_{CM} = (V–)+2V to (V+)–2V	120	138		*	*		dB
T_A = –40°C to +85°C		**120**			*			dB
INPUT IMPEDANCE								
Differential			10^7 || 12			*		Ω || pF
Common-Mode	V_{CM} = (V–)+2V to (V+)–2V		10^9 || 3			*		Ω || pF
OPEN-LOOP GAIN								
Open-Loop Voltage Gain A_{OL}	V_O = (V–)+2V to (V+)–2V, R_L = 10kΩ	132	160		*	*		dB
T_A = –40°C to +85°C		**132**			*			dB
	V_O = (V–)+3.5V to (V+)–3.5V, R_L = 600Ω	132	160		*	*		dB
T_A = –40°C to +85°C		**132**			*			dB
FREQUENCY RESPONSE								
Minimum Closed-Loop Gain			5			*		V/V
Gain Bandwidth Product GBW			33			*		MHz
Slew Rate SR			11			*		V/µs
Settling Time: 0.1%	G = 5, 10V Step, C_L = 100pF, C_F =12pF		1.5			*		µs
0.01%	G = 5, 10V Step, C_L = 100pF, C_F =12pF		2			*		µs
Overload Recovery Time	V_{IN} • G = V_S		0.6			*		µs
Total Harmonic Distortion + Noise THD+N	f = 1kHz, G = 5, V_O = 3.5Vrms		0.00005			*		%
OUTPUT								
Voltage Output	R_L = 10kΩ	(V–)+2		(V+)–2	*		*	V
T_A = –40°C to +85°C	R_L = 10kΩ	**(V–)+2**		**(V+)–2**	*		*	V
	R_L = 600Ω	(V–)+3.5		(V+)–3.5	*		*	V
T_A = –40°C to +85°C	R_L = 600Ω	**(V–)+3.5**		**(V+)–3.5**	*		*	V
Short-Circuit Current I_{SC}			±45			*		mA
Capacitive Load Drive C_{LOAD}	See Typical Curve					*		
POWER SUPPLY								
Specified Voltage Range V_S		±5		±15	*		*	V
Operating Voltage Range		±2.5		±18	*		*	V
Quiescent Current (per amplifier) I_Q	I_O = 0		±3.7	±3.8		*	*	mA
T_A = –40°C to +85°C	I_O = 0			**±4.2**			*	mA
TEMPERATURE RANGE								
Specified Range		–40		+85	*		*	°C
Operating Range		–55		+125	*		*	°C
Storage Range		–65		+150	*		*	°C
Thermal Resistance θ_{JA}								
SO-8 Surface Mount			150			*		°C/W
DIP-8			100			*		°C/W
DIP-14			80			*		°C/W
SO-14 Surface Mount			100			*		°C/W

* Specifications same as OPA228P, U.

ABSOLUTE MAXIMUM RATINGS[1]

Supply Voltage	±18V
Signal Input Terminals, Voltage	(V–) –0.7V to (V+) +0.7V
Current	20mA
Output Short-Circuit[2]	Continuous
Operating Temperature	–55°C to +125°C
Storage Temperature	–65°C to +150°C
Junction Temperature	150°C
Lead Temperature (soldering, 10s)	300°C

NOTE: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. (2) Short-circuit to ground, one amplifier per package.

PACKAGE/ORDERING INFORMATION

For the most current package and ordering information, see the Package Option Addendum located at the end of this datasheet, or refer to our web site at www.ti.com.

ELECTROSTATIC DISCHARGE SENSITIVITY

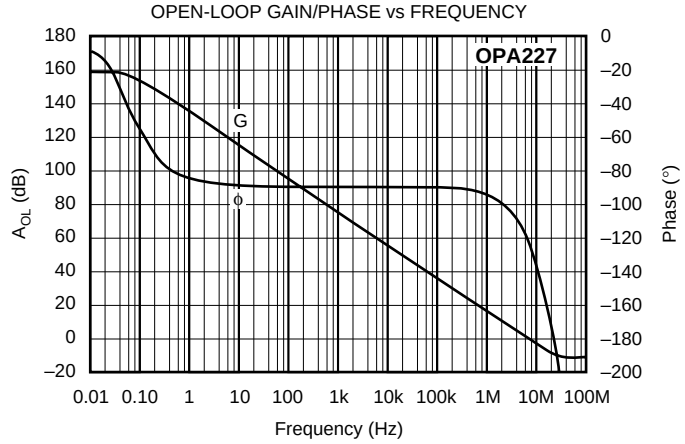
This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

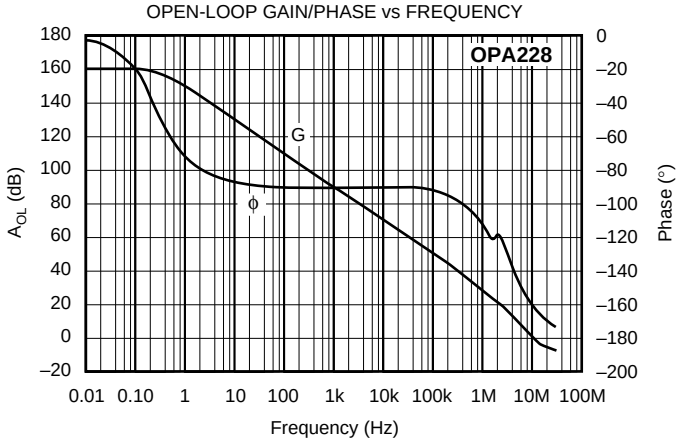
TYPICAL PERFORMANCE CURVES

At T_A = +25°C, R_L = 10kΩ, and V_S = ±15V, unless otherwise noted.

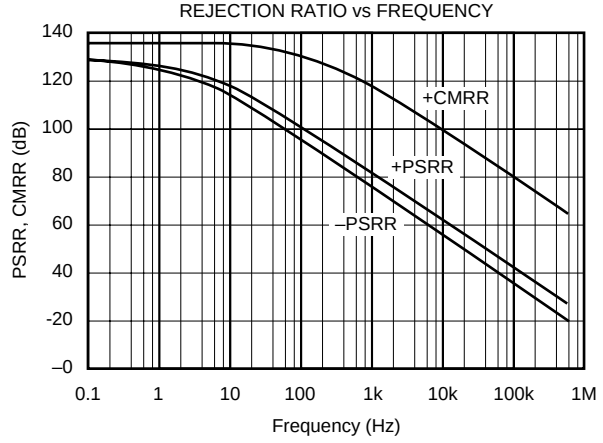
OPEN-LOOP GAIN/PHASE vs FREQUENCY



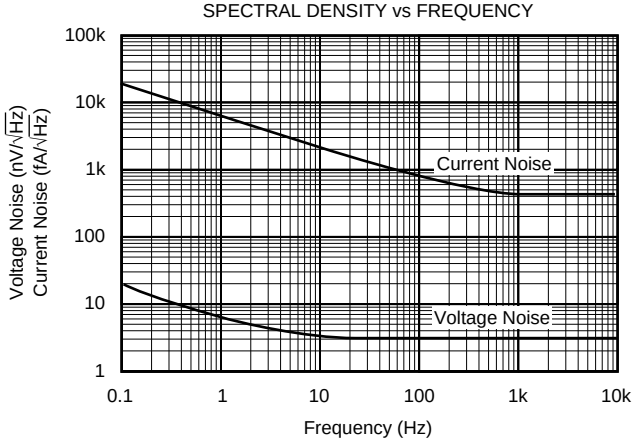
OPEN-LOOP GAIN/PHASE vs FREQUENCY



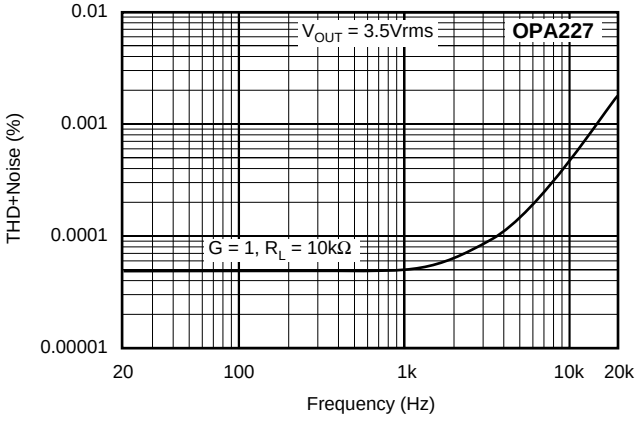
POWER SUPPLY AND COMMON-MODE REJECTION RATIO vs FREQUENCY



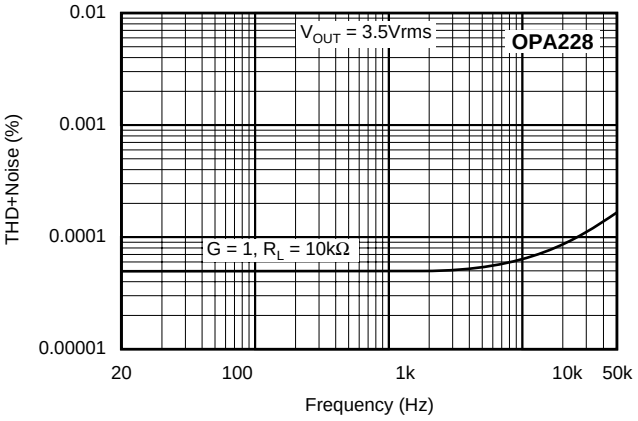
INPUT VOLTAGE AND CURRENT NOISE SPECTRAL DENSITY vs FREQUENCY



TOTAL HARMONIC DISTORTION + NOISE vs FREQUENCY



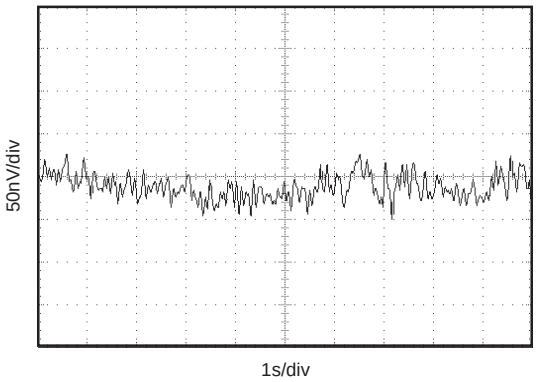
TOTAL HARMONIC DISTORTION + NOISE vs FREQUENCY



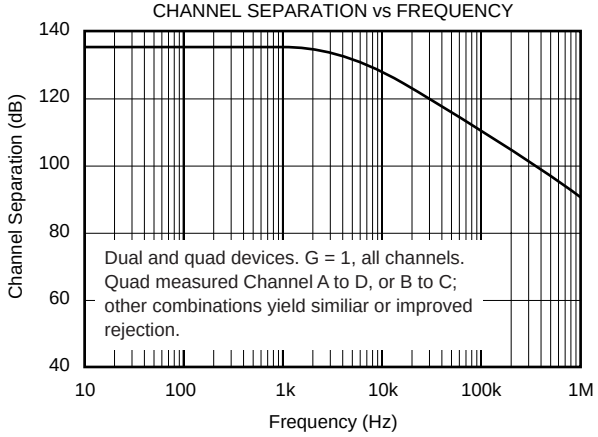
TYPICAL PERFORMANCE CURVES (CONT)

At T_A = +25°C, R_L =10kΩ, and V_S = ±15V, unless otherwise noted.

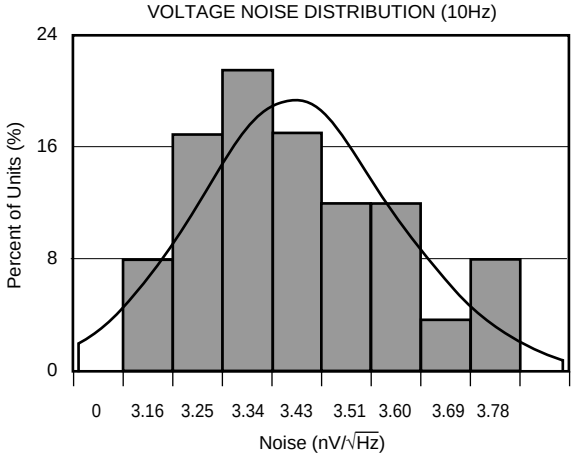
INPUT NOISE VOLTAGE vs TIME



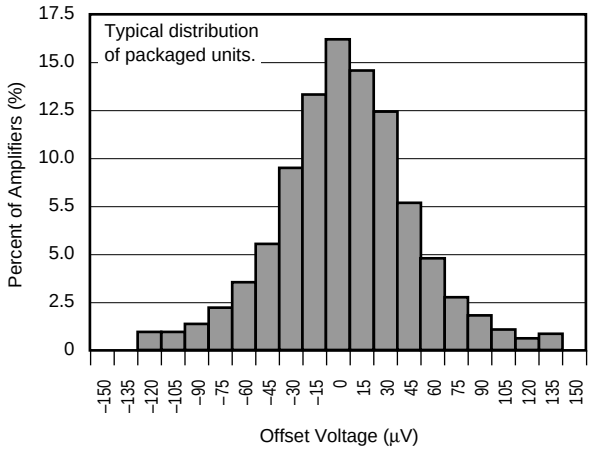
CHANNEL SEPARATION vs FREQUENCY



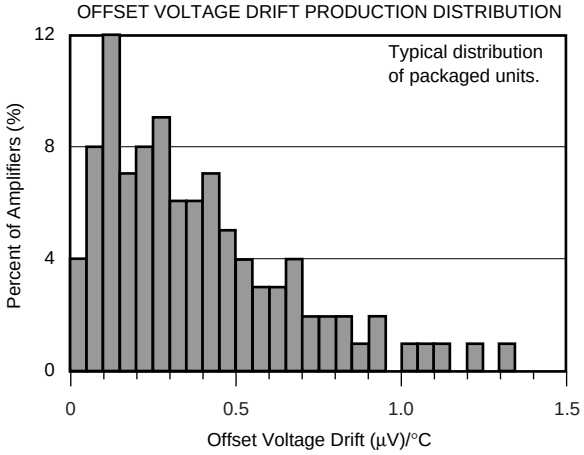
VOLTAGE NOISE DISTRIBUTION (10Hz)



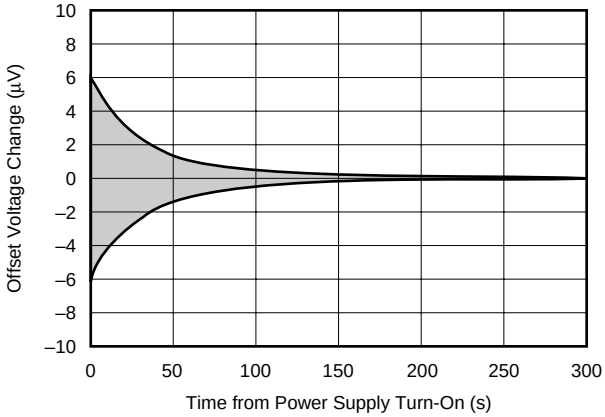
OFFSET VOLTAGE PRODUCTION DISTRIBUTION



OFFSET VOLTAGE DRIFT PRODUCTION DISTRIBUTION



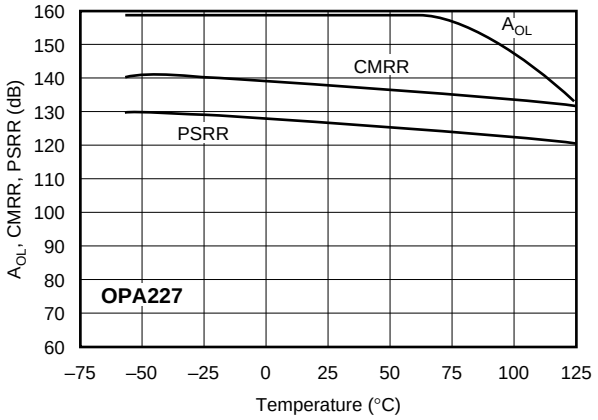
WARM-UP OFFSET VOLTAGE DRIFT



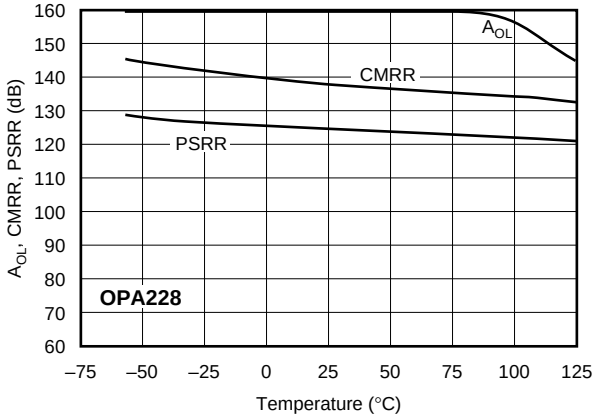
TYPICAL PERFORMANCE CURVES (CONT)

At T_A = +25°C, R_L = 10kΩ, and V_S = ±15V, unless otherwise noted.

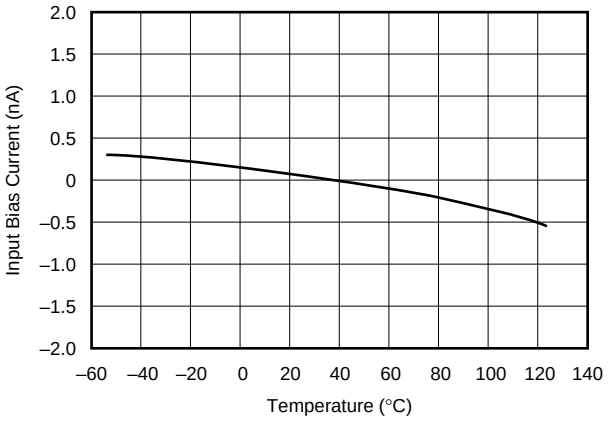
A_{OL}, CMRR, PSRR vs TEMPERATURE



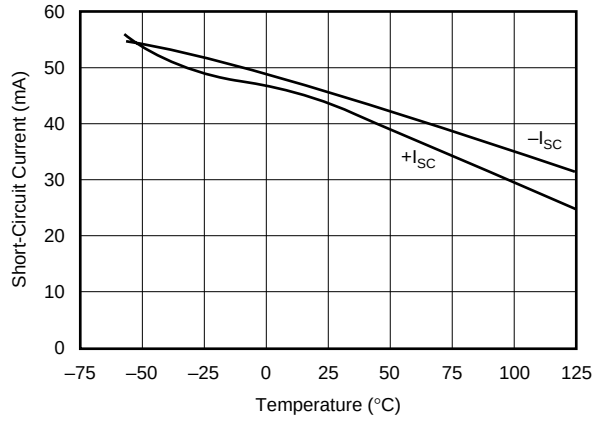
A_{OL}, CMRR, PSRR vs TEMPERATURE



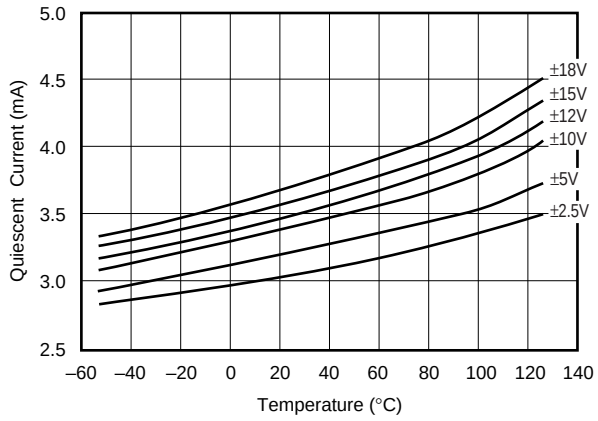
INPUT BIAS CURRENT vs TEMPERATURE



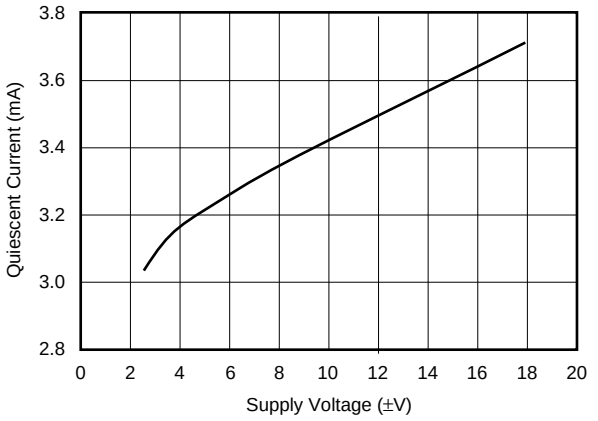
SHORT-CIRCUIT CURRENT vs TEMPERATURE



QUIESCENT CURRENT vs TEMPERATURE



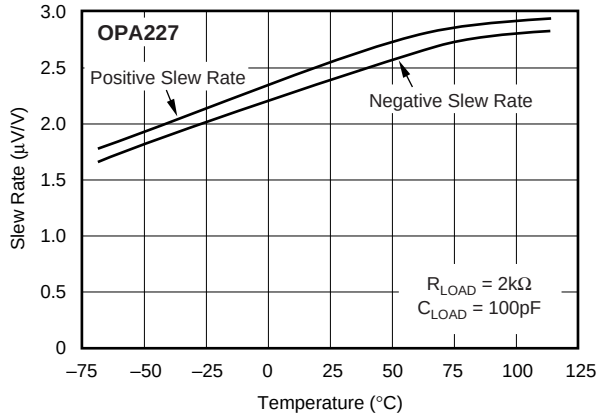
QUIESCENT CURRENT vs SUPPLY VOLTAGE



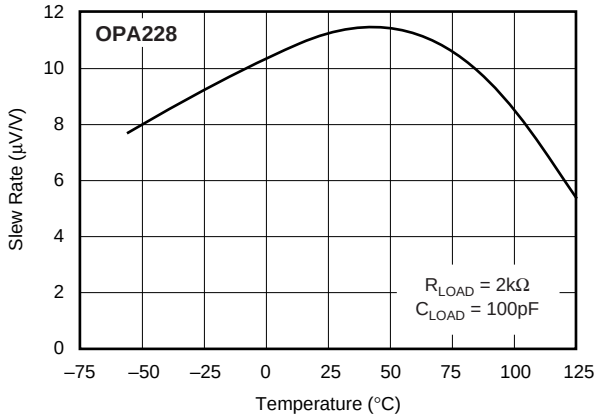
TYPICAL PERFORMANCE CURVES (CONT)

At T_A = +25°C, R_L = 10kΩ, and V_S = ±15V, unless otherwise noted.

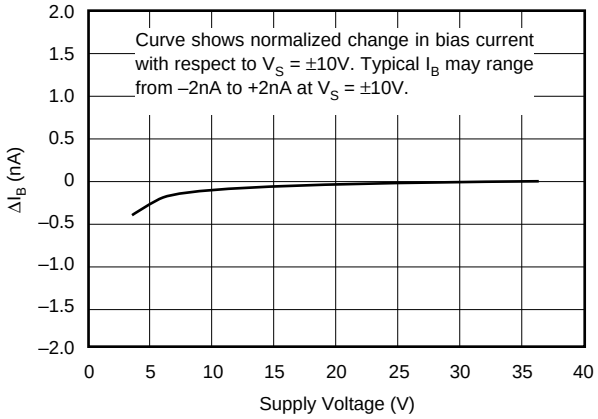
SLEW RATE vs TEMPERATURE



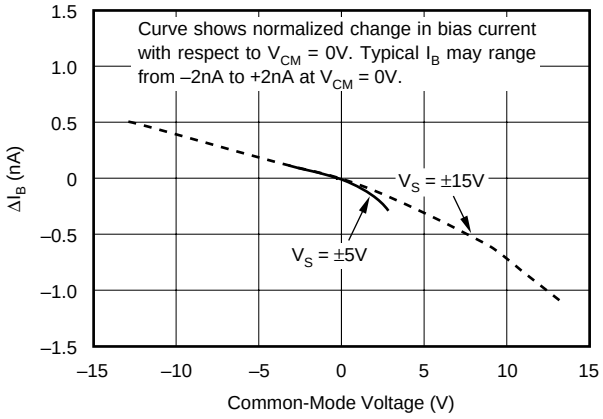
SLEW RATE vs TEMPERATURE



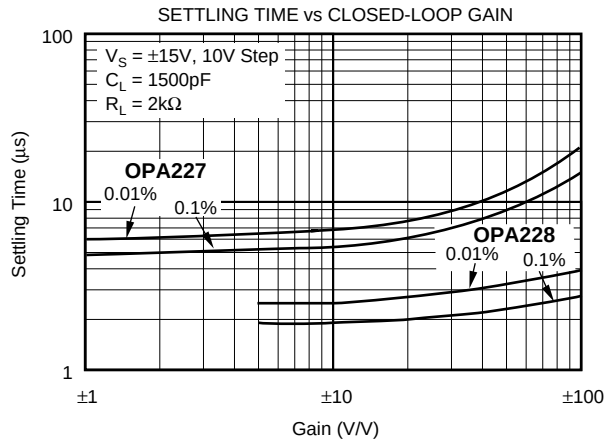
CHANGE IN INPUT BIAS CURRENT vs POWER SUPPLY VOLTAGE



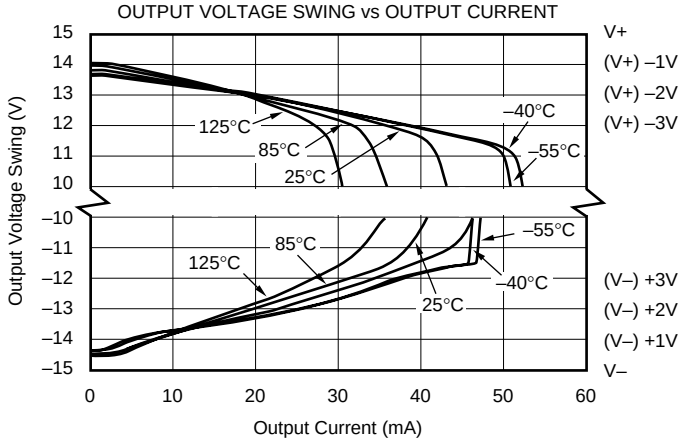
CHANGE IN INPUT BIAS CURRENT vs COMMON-MODE VOLTAGE



SETTLING TIME vs CLOSED-LOOP GAIN



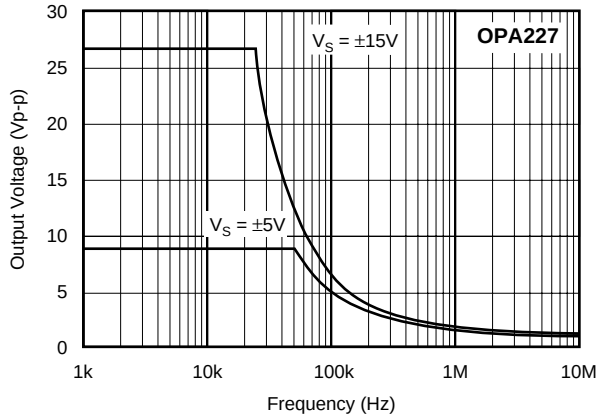
OUTPUT VOLTAGE SWING vs OUTPUT CURRENT



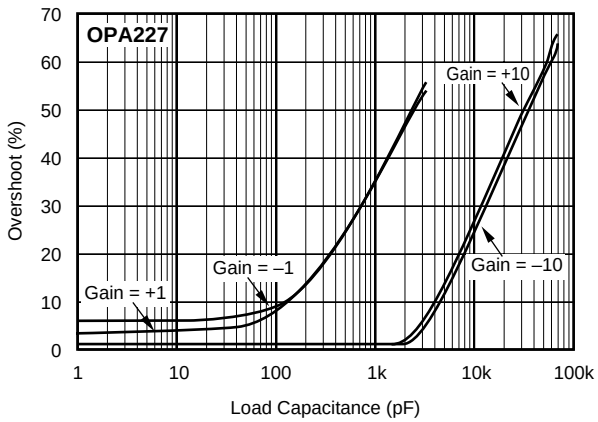
TYPICAL PERFORMANCE CURVES (CONT)

At T_A = +25°C, R_L = 10kΩ, and V_S = ±15V, unless otherwise noted.

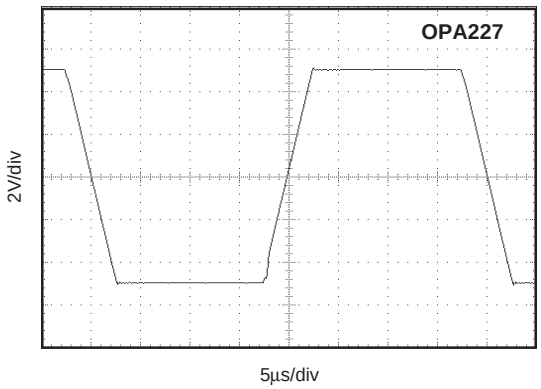
MAXIMUM OUTPUT VOLTAGE vs FREQUENCY



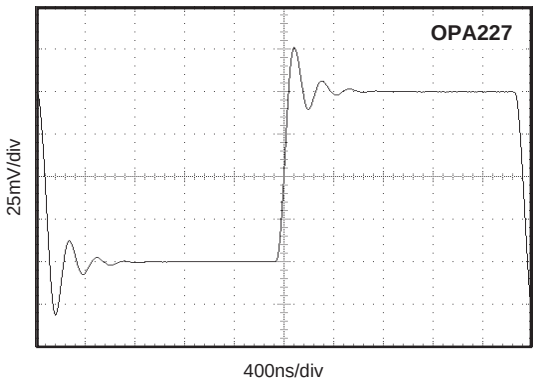
SMALL-SIGNAL OVERSHOOT vs LOAD CAPACITANCE



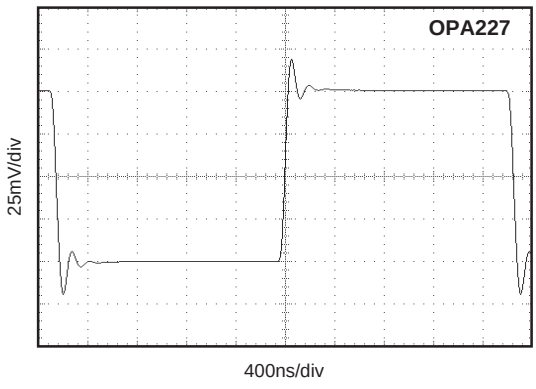
LARGE-SIGNAL STEP RESPONSE
G = –1, C_L = 1500pF



SMALL-SIGNAL STEP RESPONSE
G = +1, C_L = 1000pF



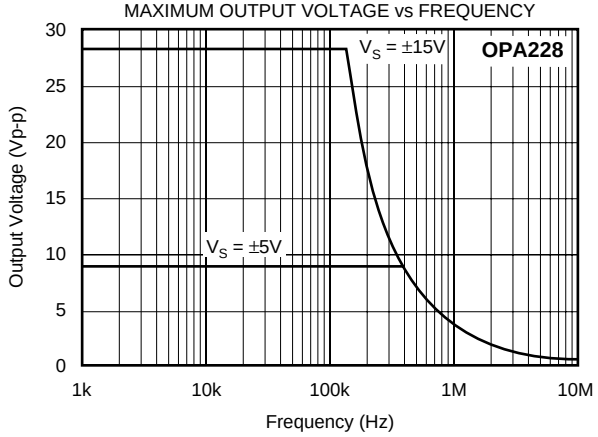
SMALL-SIGNAL STEP RESPONSE
G = +1, C_L = 5pF



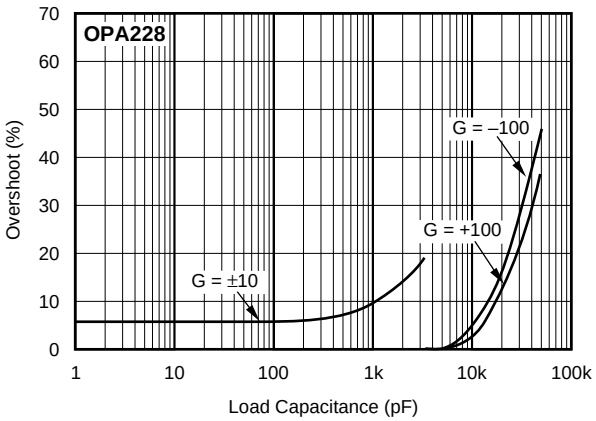
TYPICAL PERFORMANCE CURVES (CONT)

At T_A = +25°C, R_L = 10kΩ, and V_S = ±15V, unless otherwise noted.

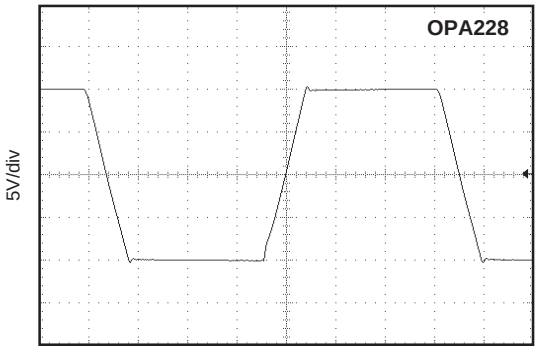
MAXIMUM OUTPUT VOLTAGE vs FREQUENCY



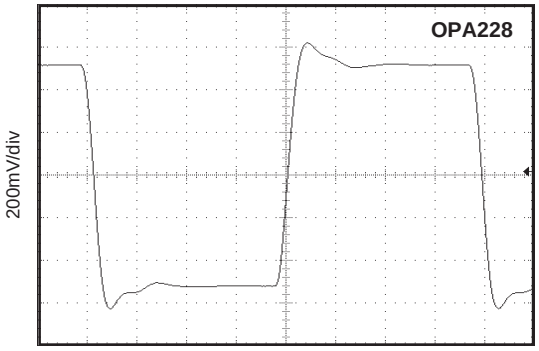
SMALL-SIGNAL OVERSHOOT vs LOAD CAPACITANCE



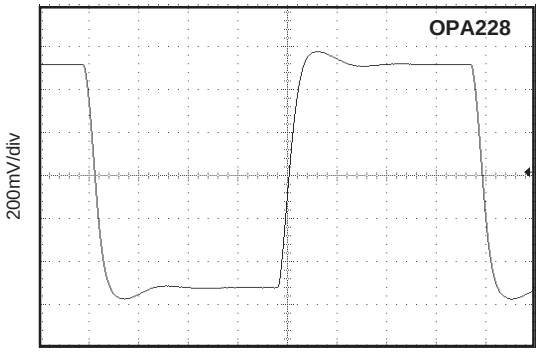
LARGE-SIGNAL STEP RESPONSE
G = –10, C_L = 100pF



SMALL-SIGNAL STEP RESPONSE
G = +10, C_L = 1000pF, R_L = 1.8kΩ



SMALL-SIGNAL STEP RESPONSE
G = +10, C_L = 5pF, R_L = 1.8kΩ



APPLICATIONS INFORMATION

The OPA227 and OPA228 series are precision op amps with very low noise. The OPA227 series is unity-gain stable with a slew rate of 2.3V/µs and 8MHz bandwidth. The OPA228 series is optimized for higher-speed applications with gains of 5 or greater, featuring a slew rate of 10V/µs and 33MHz bandwidth. Applications with noisy or high impedance power supplies may require decoupling capacitors close to the device pins. In most cases, 0.1µF capacitors are adequate.

OFFSET VOLTAGE AND DRIFT

The OPA227 and OPA228 series have very low offset voltage and drift. To achieve highest dc precision, circuit layout and mechanical conditions should be optimized. Connections of dissimilar metals can generate thermal potentials at the op amp inputs which can degrade the offset voltage and drift. These thermocouple effects can exceed the inherent drift of the amplifier and ultimately degrade its performance. The thermal potentials can be made to cancel by assuring that they are equal at both input terminals. In addition:

- Keep thermal mass of the connections made to the two input terminals similar.
- Locate heat sources as far as possible from the critical input circuitry.
- Shield op amp and input circuitry from air currents such as those created by cooling fans.

OPERATING VOLTAGE

OPA227 and OPA228 series op amps operate from ±2.5V to ±18V supplies with excellent performance. Unlike most op amps which are specified at only one supply voltage, the OPA227 series is specified for real-world applications; a single set of specifications applies over the ±5V to ±15V supply range. Specifications are assured for applications between ±5V and ±15V power supplies. Some applications do not require equal positive and negative output voltage swing. Power supply voltages do not need to be equal. The OPA227 and OPA228 series can operate with as little as 5V between the supplies and with up to 36V between the supplies. For example, the positive supply could be set to 25V with the negative supply at –5V or vice-versa. In addition, key parameters are assured over the specified temperature range, –40°C to +85°C. Parameters which vary significantly with operating voltage or temperature are shown in the Typical Performance Curves.

OFFSET VOLTAGE ADJUSTMENT

The OPA227 and OPA228 series are laser-trimmed for very low offset and drift so most applications will not require external adjustment. However, the OPA227 and OPA228 (single versions) provide offset voltage trim connections on pins 1 and 8. Offset voltage can be adjusted by connecting a potentiometer as shown in Figure 1. This adjustment should be used only to null the offset of the op amp. This adjustment should not be used to compensate for offsets created elsewhere in the system since this can introduce additional temperature drift.

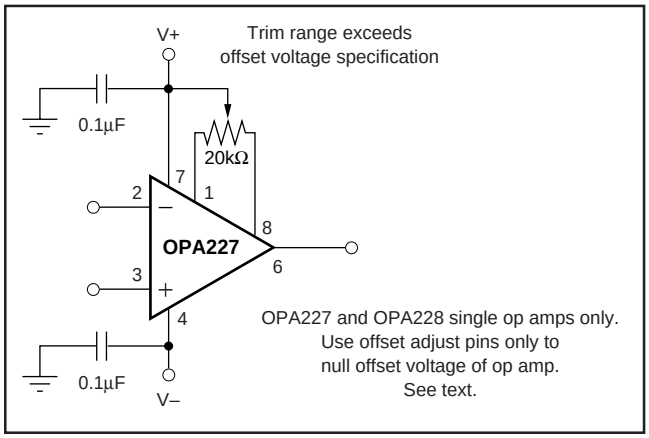


FIGURE 1. OPA227 Offset Voltage Trim Circuit.

INPUT PROTECTION

Back-to-back diodes (see Figure 2) are used for input protection on the OPA227 and OPA228. Exceeding the turn-on threshold of these diodes, as in a pulse condition, can cause current to flow through the input protection diodes due to the amplifier's finite slew rate. Without external current-limiting resistors, the input devices can be destroyed. Sources of high input current can cause subtle damage to the amplifier. Although the unit may still be functional, important parameters such as input offset voltage, drift, and noise may shift.

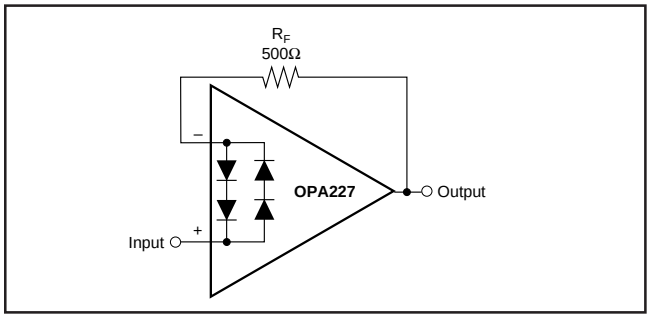


FIGURE 2. Pulsed Operation.

When using the OPA227 as a unity-gain buffer (follower), the input current should be limited to 20mA. This can be accomplished by inserting a feedback resistor or a resistor in series with the source. Sufficient resistor size can be calculated:

$$R_X = V_S/20mA - R_{SOURCE}$$

where R_X is either in series with the source or inserted in the feedback path. For example, for a 10V pulse (V_S = 10V), total loop resistance must be 500Ω. If the source impedance is large enough to sufficiently limit the current on its own, no additional resistors are needed. The size of any external resistors must be carefully chosen since they will increase noise. See the Noise Performance section of this data sheet for further information on noise calculation. Figure 2 shows an example implementing a current-limiting feedback resistor.

INPUT BIAS CURRENT CANCELLATION

The input bias current of the OPA227 and OPA228 series is internally compensated with an equal and opposite cancellation current. The resulting input bias current is the difference between with input bias current and the cancellation current. The residual input bias current can be positive or negative.

When the bias current is cancelled in this manner, the input bias current and input offset current are approximately equal. A resistor added to cancel the effect of the input bias current (as shown in Figure 3) may actually increase offset and noise and is therefore not recommended.

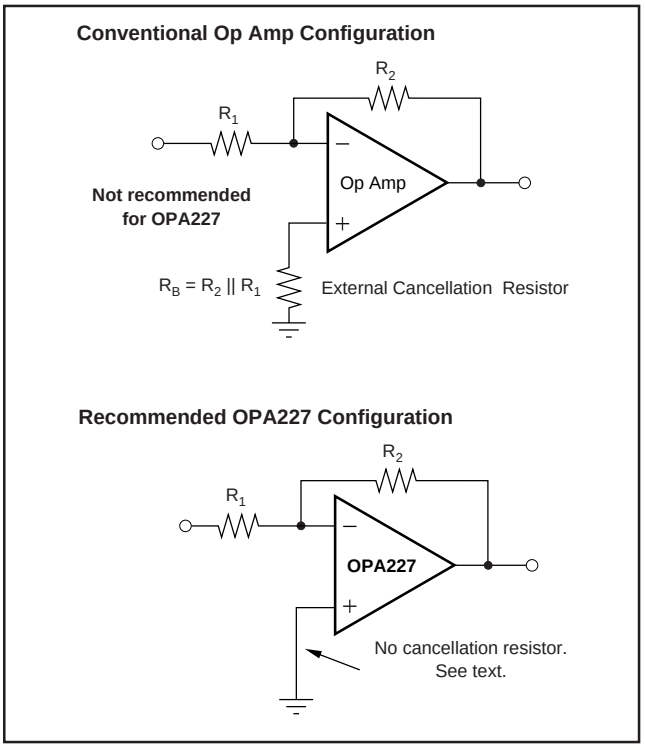


FIGURE 3. Input Bias Current Cancellation.

NOISE PERFORMANCE

Figure 4 shows total circuit noise for varying source impedances with the op amp in a unity-gain configuration (no feedback resistor network, therefore no additional noise contributions). Two different op amps are shown with total circuit noise calculated. The OPA227 has very low voltage noise, making it ideal for low source impedances (less than 20kΩ). A similar precision op amp, the OPA277, has somewhat higher voltage noise but lower current noise. It provides excellent noise performance at moderate source impedance (10kΩ to 100kΩ). Above 100kΩ, a FET-input op amp such as the OPA132 (very low current noise) may provide improved performance. The equation is shown for the calculation of the total circuit noise. Note that e_n = voltage noise, i_n = current noise, R_S = source impedance, k = Boltzmann's constant = $1.38 \cdot 10^{-23}$ J/K and T is temperature in K. For more details on calculating noise, see the insert titled "Basic Noise Calculations."

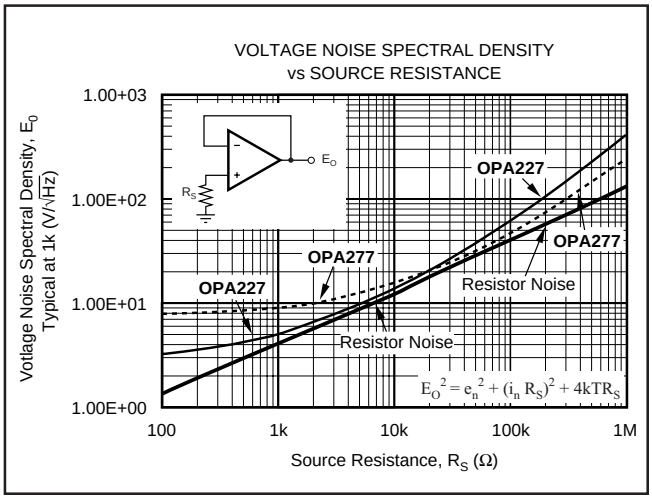


FIGURE 4. Noise Performance of the OPA227 in Unity-Gain Buffer Configuration.

BASIC NOISE CALCULATIONS

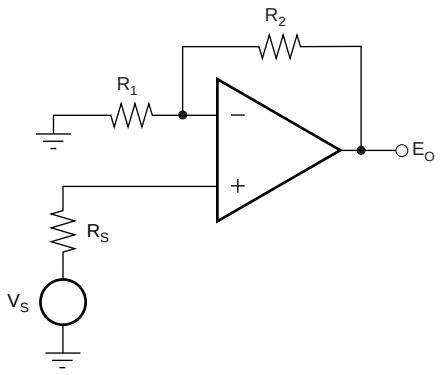
Design of low noise op amp circuits requires careful consideration of a variety of possible noise contributors: noise from the signal source, noise generated in the op amp, and noise from the feedback network resistors. The total noise of the circuit is the root-sum-square combination of all noise components.

The resistive portion of the source impedance produces thermal noise proportional to the square root of the resistance. This function is shown plotted in Figure 4. Since the source impedance is usually fixed, select the op amp and the feedback resistors to minimize their contribution to the total noise.

Figure 4 shows total noise for varying source impedances with the op amp in a unity-gain configuration (no feedback resistor network and therefore no additional noise contributions). The operational amplifier itself contributes both a voltage noise component and a current noise component. The voltage noise is commonly modeled as a time-varying component of the offset voltage. The current noise is modeled as the time-varying component of the input bias current and reacts with the source resistance to create a voltage component of noise. Consequently, the lowest noise op amp for a given application depends on the source impedance. For low source impedance, current noise is negligible and voltage noise generally dominates. For high source impedance, current noise may dominate.

Figure 5 shows both inverting and noninverting op amp circuit configurations with gain. In circuit configurations with gain, the feedback network resistors also contribute noise. The current noise of the op amp reacts with the feedback resistors to create additional noise components. The feedback resistor values can generally be chosen to make these noise sources negligible. The equations for total noise are shown for both configurations.

Noise in Noninverting Gain Configuration



Noise at the output:

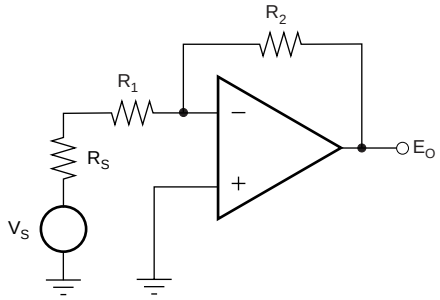
$$E_O^2 = \left(1+\frac{R_2}{R_1}\right)^2 e_n^2 + e_1^2 + e_2^2 + (i_n R_2)^2 + e_S^2 + (i_n R_S)^2\left(1+\frac{R_2}{R_1}\right)^2$$

Where $e_S = \sqrt{4kTR_S} \bullet \left(1+\frac{R_2}{R_1}\right)$ = thermal noise of R_S

$e_1 = \sqrt{4kTR_1} \bullet \left(\frac{R_2}{R_1}\right)$ = thermal noise of R_1

$e_2 = \sqrt{4kTR_2}$ = thermal noise of R_2

Noise in Inverting Gain Configuration



Noise at the output:

$$E_O^2 = \left(1+\frac{R_2}{R_1+R_S}\right)^2 e_n^2 + e_1^2 + e_2^2 + (i_n R_2)^2 + e_S^2$$

Where $e_S = \sqrt{4kTR_S} \bullet \left(\frac{R_2}{R_1+R_S}\right)$ = thermal noise of R_S

$e_1 = \sqrt{4kTR_1} \bullet \left(\frac{R_2}{R_1+R_S}\right)$ = thermal noise of R_1

$e_2 = \sqrt{4kTR_2}$ = thermal noise of R_2

For the OPA227 and OPA228 series op amps at 1kHz, $e_n = 3nV/\sqrt{Hz}$ and $i_n = 0.4pA/\sqrt{Hz}$.

FIGURE 5. Noise Calculation in Gain Configurations.

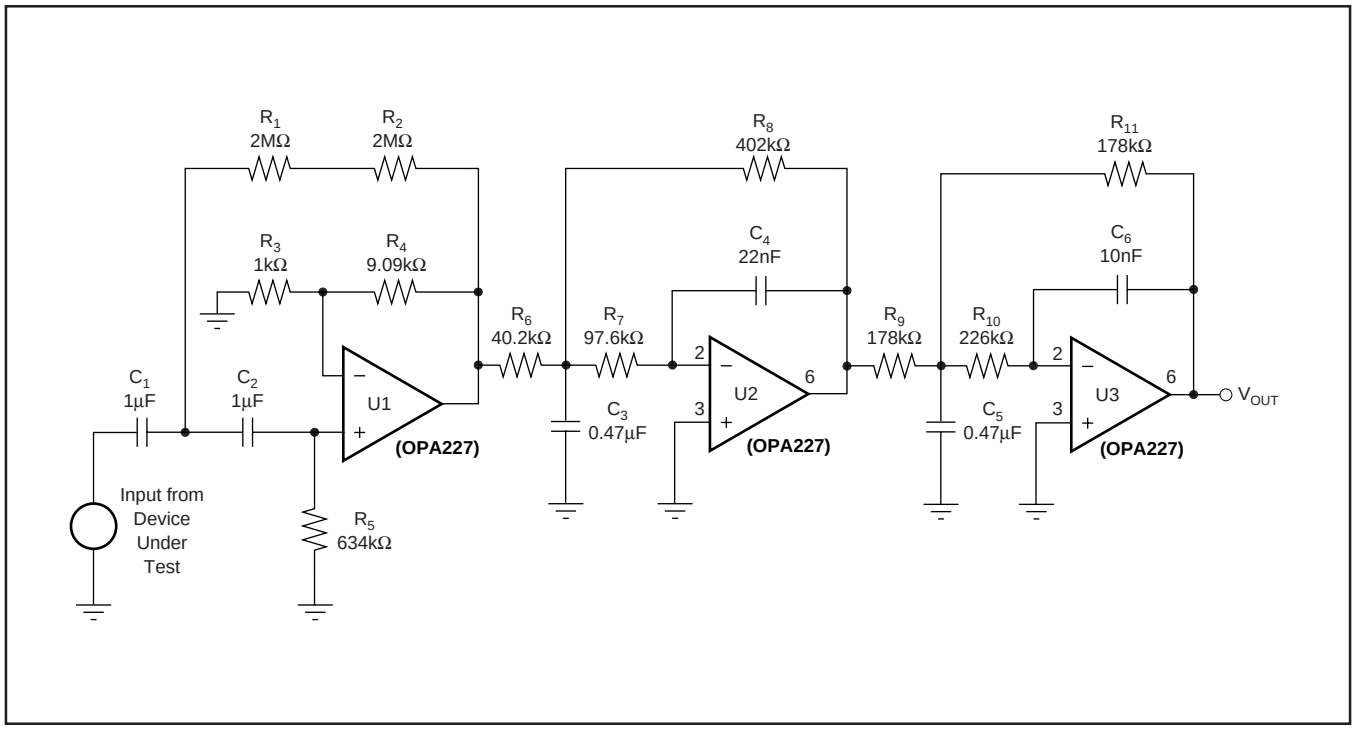


FIGURE 6. 0.1Hz to 10Hz Bandpass Filter Used to Test Wideband Noise of the OPA227 and OPA228 Series.

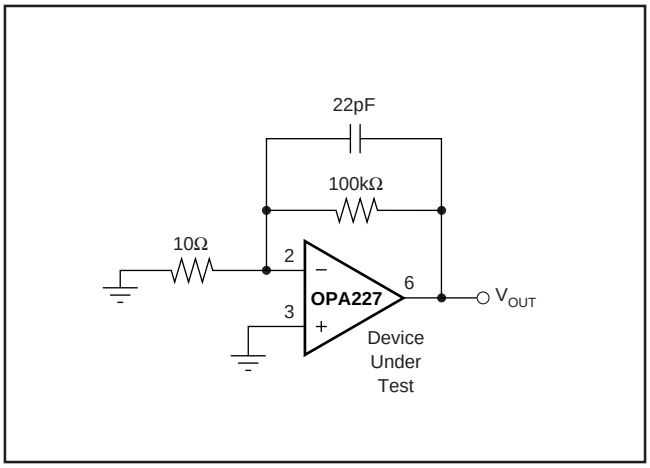


FIGURE 7. Noise Test Circuit.

Figure 6 shows the 0.1Hz 10Hz bandpass filter used to test the noise of the OPA227 and OPA228. The filter circuit was designed using Texas Instruments' FilterPro software (available at www.ti.com). Figure 7 shows the configuration of the OPA227 and OPA228 for noise testing.

USING THE OPA228 IN LOW GAINS

The OPA228 family is intended for applications with signal gains of 5 or greater, but it is possible to take advantage of their high speed in lower gains. Without external compensation, the OPA228 has sufficient phase margin to maintain stability in unity gain with purely resistive loads. However, the addition of load capacitance can reduce the phase margin and destabilize the op amp.

A variety of compensation techniques have been evaluated specifically for use with the OPA228. The recommended configuration consists of an additional capacitor (C_F) in parallel with the feedback resistance, as shown in Figures 8 and 11. This feedback capacitor serves two purposes in compensating the circuit. The op amp's input capacitance and the feedback resistors interact to cause phase shift that can result in instability. C_F compensates the input capacitance, minimizing peaking. Additionally, at high frequencies, the closed-loop gain of the amplifier is strongly influenced by the ratio of the input capacitance and the feedback capacitor. Thus, C_F can be selected to yield good stability while maintaining high speed.

Without external compensation, the noise specification of the OPA228 is the same as that for the OPA227 in gains of 5 or greater. With the additional external compensation, the output noise of the of the OPA228 will be higher. The amount of noise increase is directly related to the increase in high frequency closed-loop gain established by the C_{IN}/C_F ratio.

Figures 8 and 11 show the recommended circuit for gains of +2 and –2, respectively. The figures suggest approximate values for C_F. Because compensation is highly dependent on circuit design, board layout, and load conditions, C_F should be optimized experimentally for best results. Figures 9 and 10 show the large- and small-signal step responses for the G = +2 configuration with 100pF load capacitance. Figures 12 and 13 show the large- and small-signal step responses for the G = –2 configuration with 100pF load capacitance.

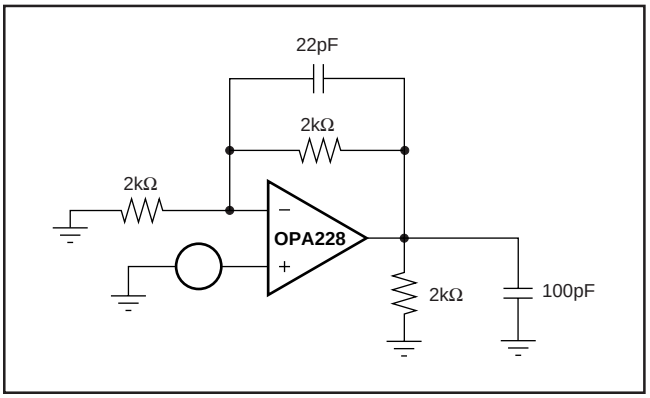


FIGURE 8. Compensation of the OPA228 for G =+2.

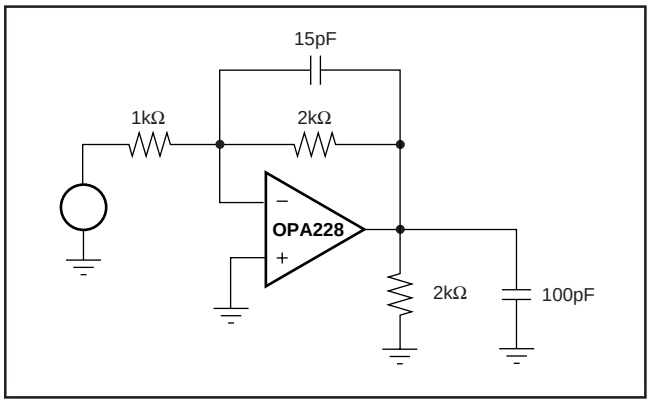


FIGURE 11. Compensation for OPA228 for G = –2.

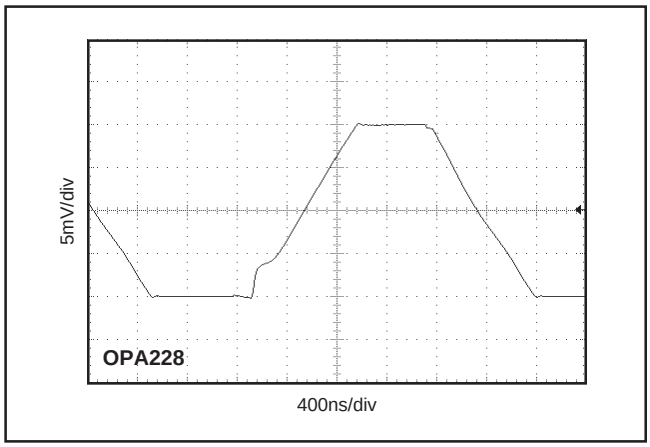


FIGURE 9. Large-Signal Step Response, G = +2, C_{LOAD} = 100pF, Input Signal = 5Vp-p.

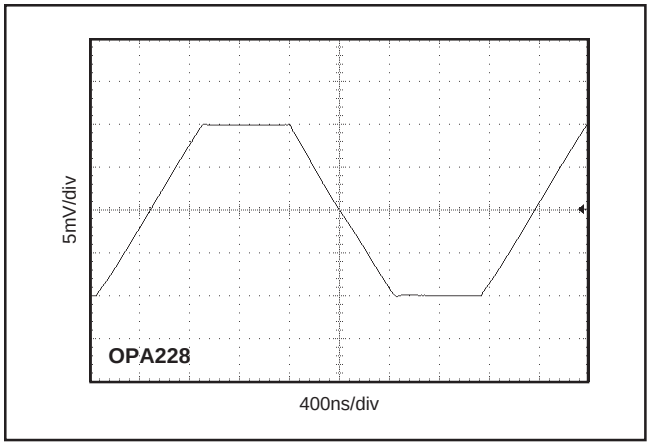


FIGURE 12. Large-Signal Step Response, G = –2, C_{LOAD} = 100pF, Input Signal = 5Vp-p.

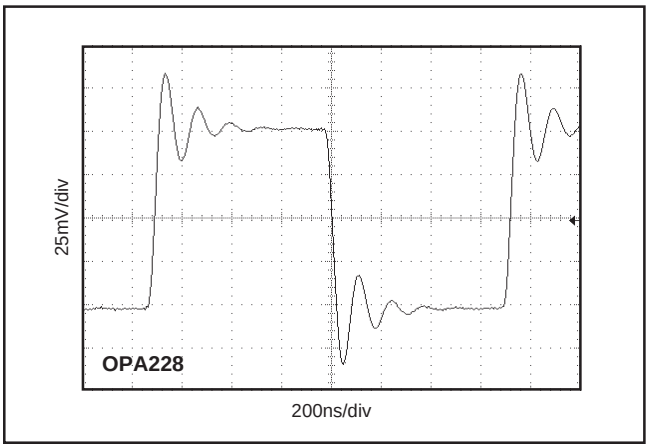


FIGURE 10. Small-Signal Step Response, G = +2, C_{LOAD} = 100pF, Input Signal = 50mVp-p.

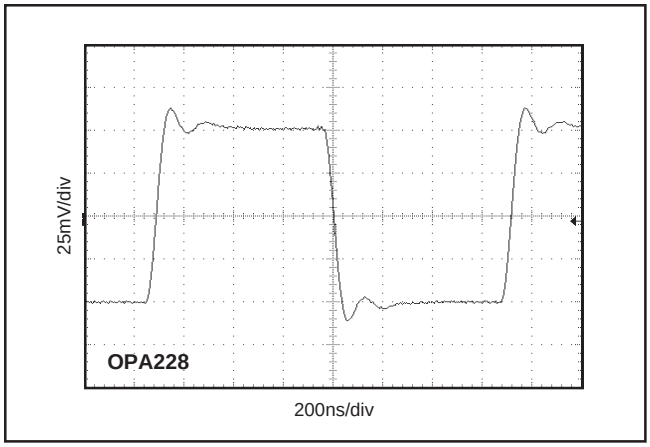


FIGURE 13. Small-Signal Step Response, G = –2, C_{LOAD} = 100pF, Input Signal = 50mVp-p.

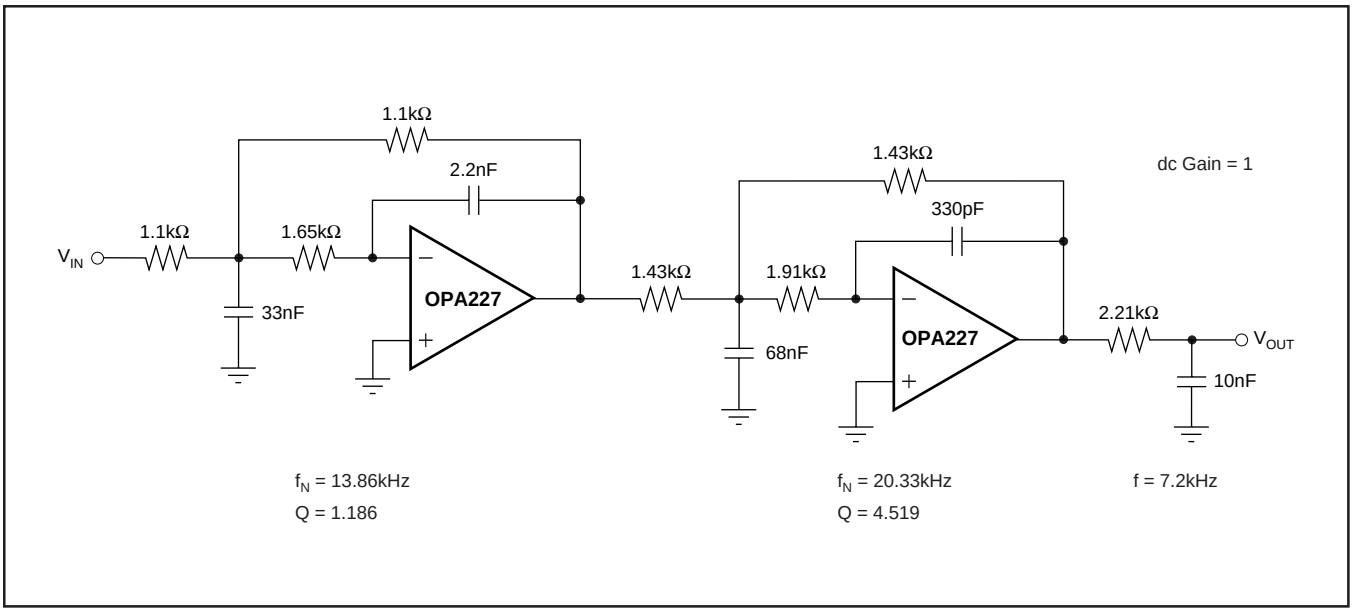


FIGURE 14. Three-Pole, 20kHz Low Pass, 0.5dB Chebyshev Filter.

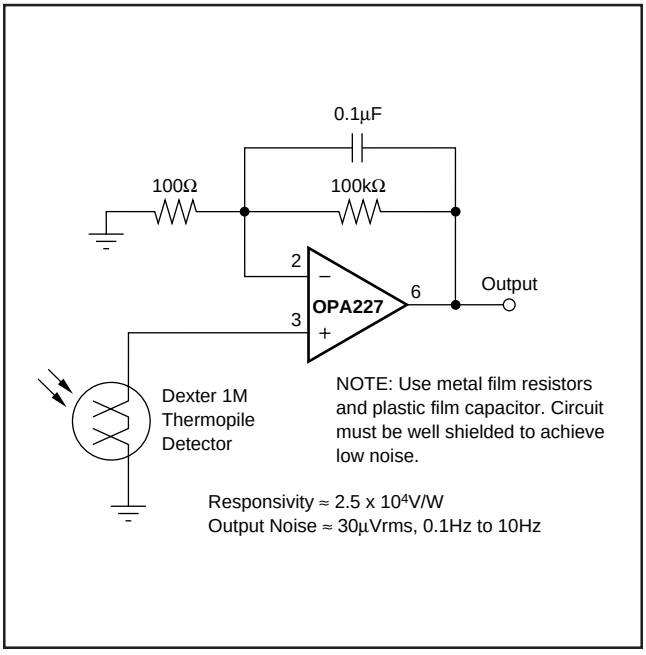


FIGURE 15. Long-Wavelength Infrared Detector Amplifier.

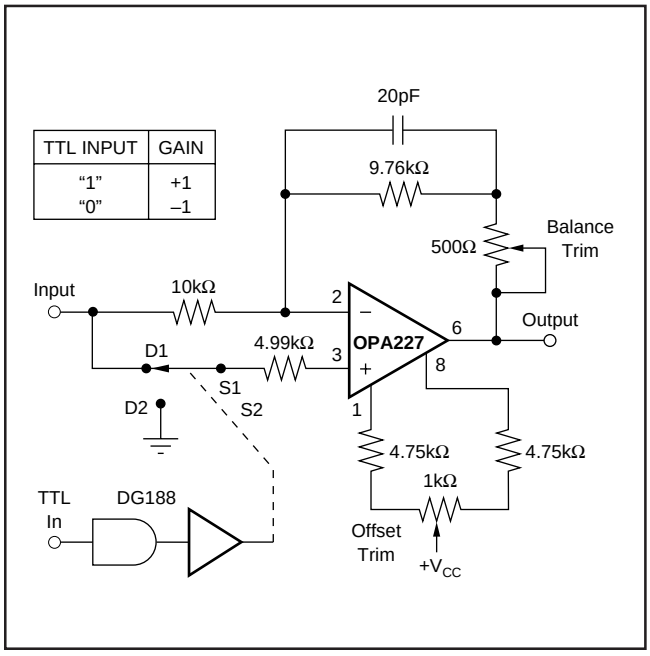


FIGURE 16. High Performance Synchronous Demodulator.

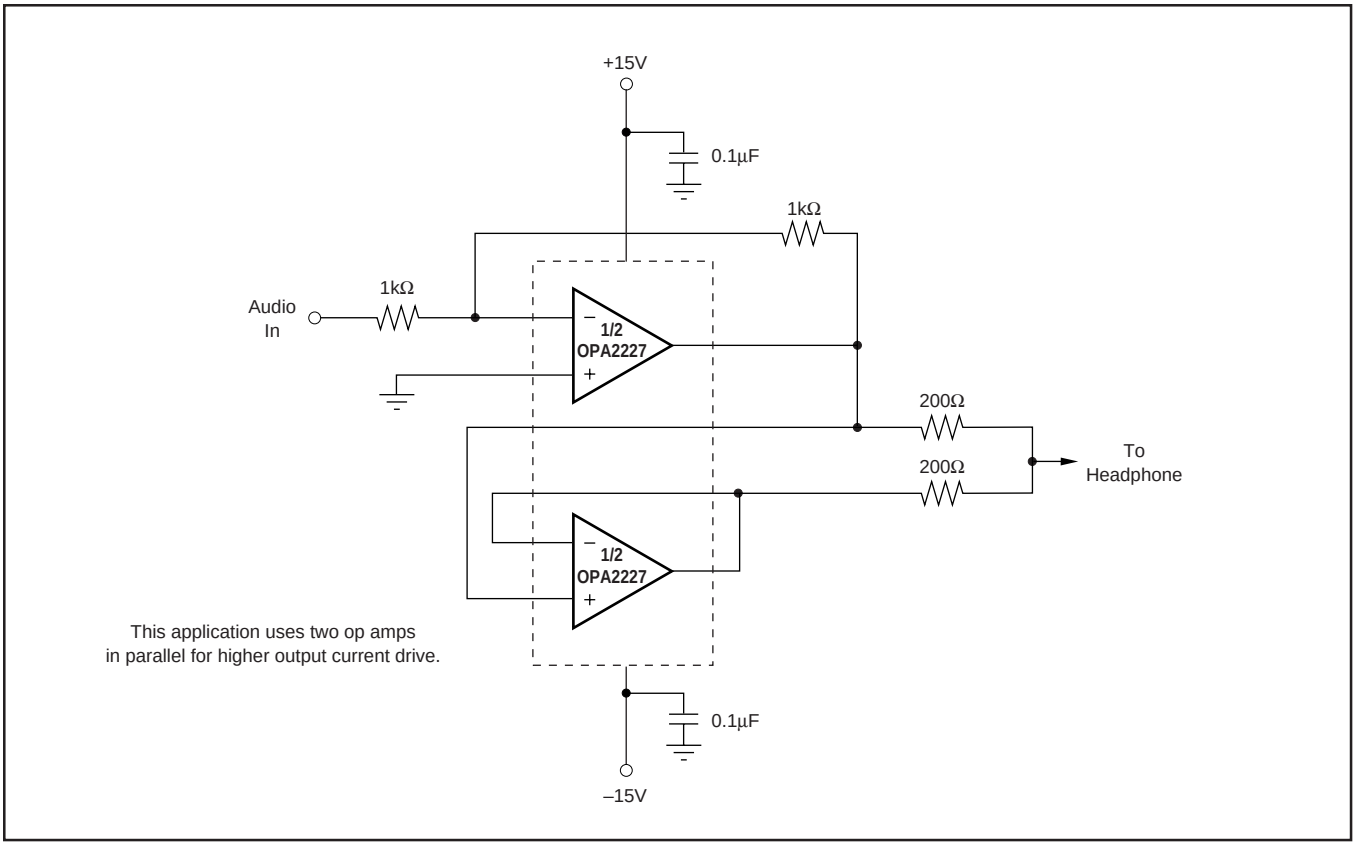


FIGURE 17. Headphone Amplifier.

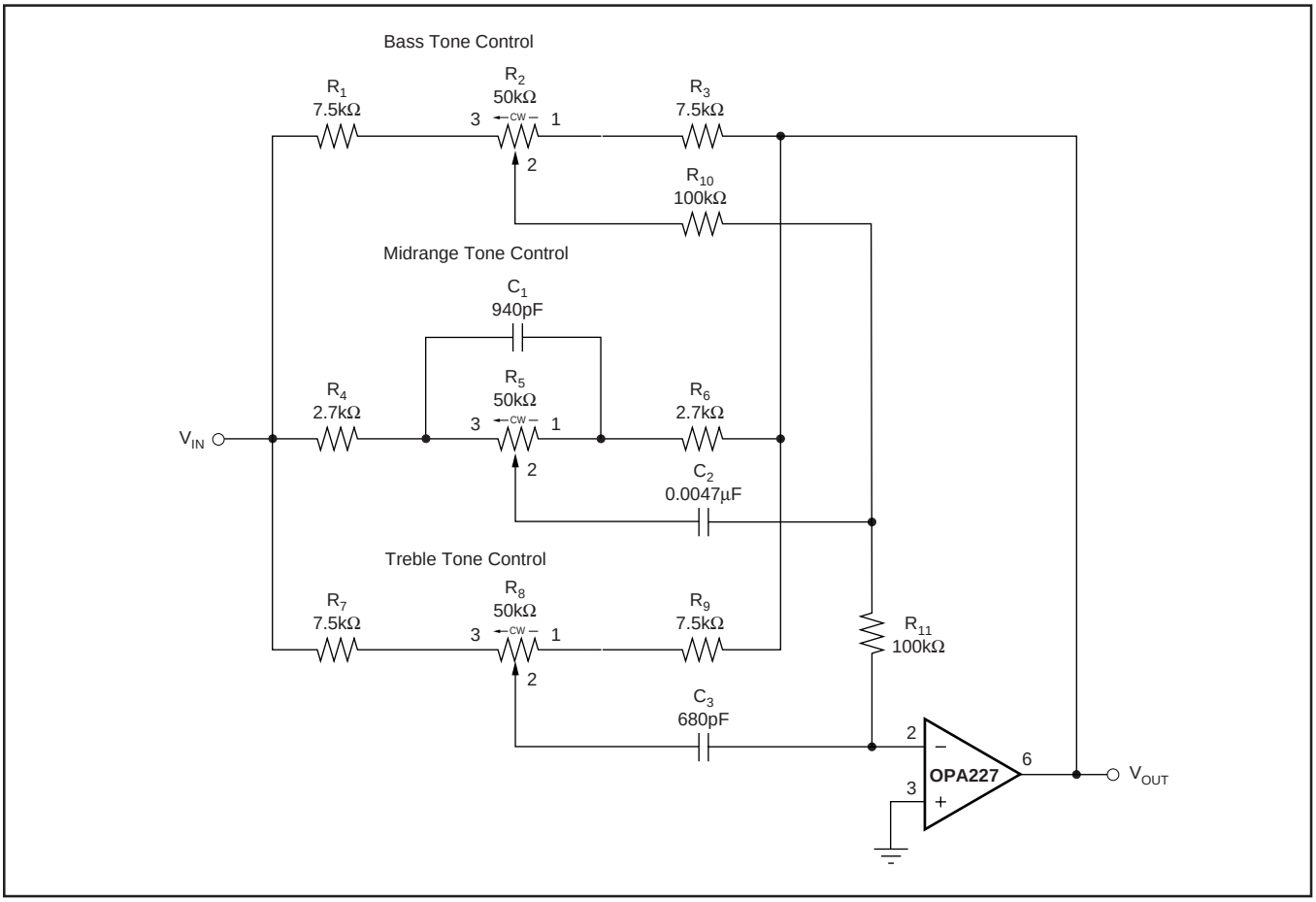


FIGURE 18. Three-Band ActiveTone Control (bass, midrange and treble).

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
OPA2227P	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA2227PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA2227PAG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA2227PG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA2227U	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2227U/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2227U/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2227UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2227UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2227UA/2K5E4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2227UAE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2227UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2227UE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2227UG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2228P	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA2228PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA2228PAG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
OPA2228PG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA2228U	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2228U/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2228U/2K5E4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2228UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2228UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2228UA/2K5E4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2228UAE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA2228UE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA227P	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA227PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA227PAG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA227PG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA227U	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA227U/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA227U/2K5E4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA227UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA227UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
OPA227UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA227UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA227UE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA228P	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA228PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA228PAG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA228PG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA228U	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA228UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA228UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA228UA/2K5E4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA228UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA228UG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA4227PA	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA4227PAG4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA4227UA	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA4227UA/2K5	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA4227UA/2K5G4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
OPA4227UAG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA4228PA	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA4228PAG4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	Add to cart
OPA4228UA	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA4228UA/2K5	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA4228UA/2K5G4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart
OPA4228UAE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Add to cart

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

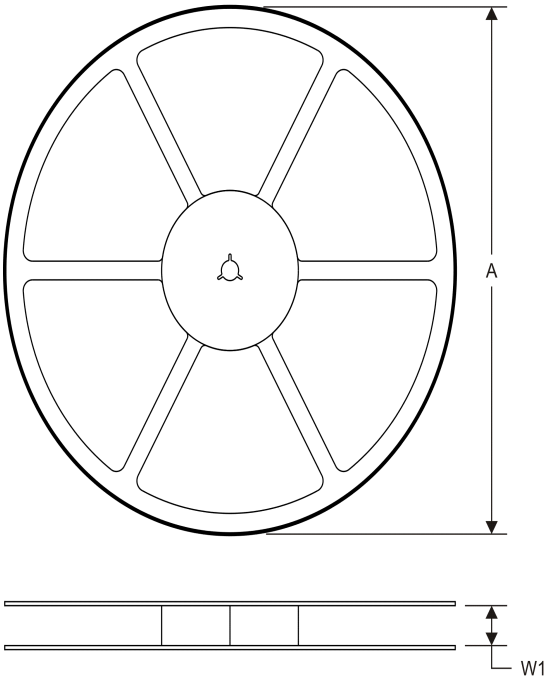
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

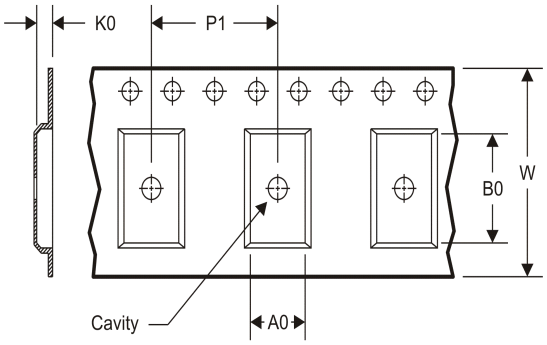
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



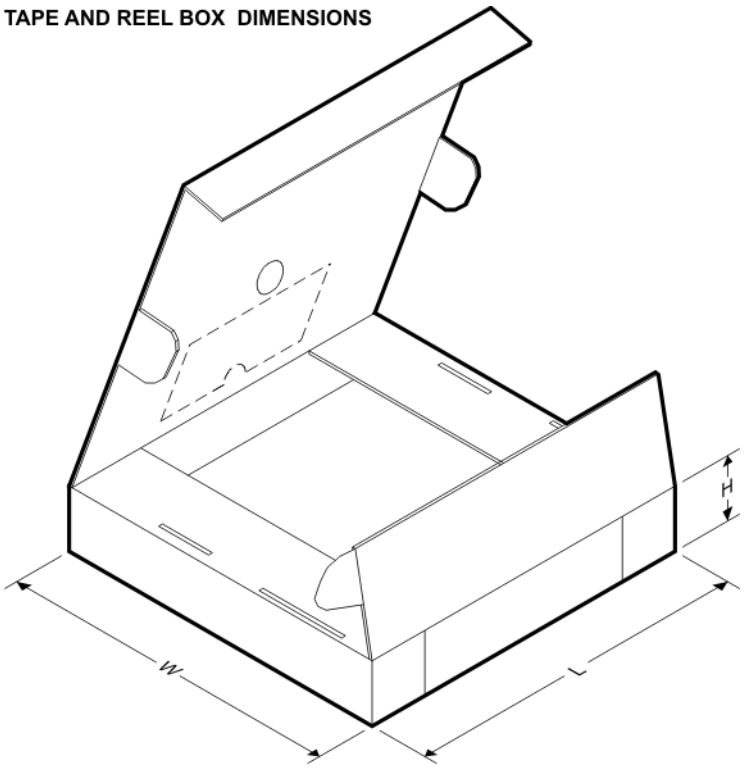
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2227U/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA2227UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA2228U/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA2228UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA227U/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA227UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA228UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4227UA/2K5	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
OPA4228UA/2K5	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

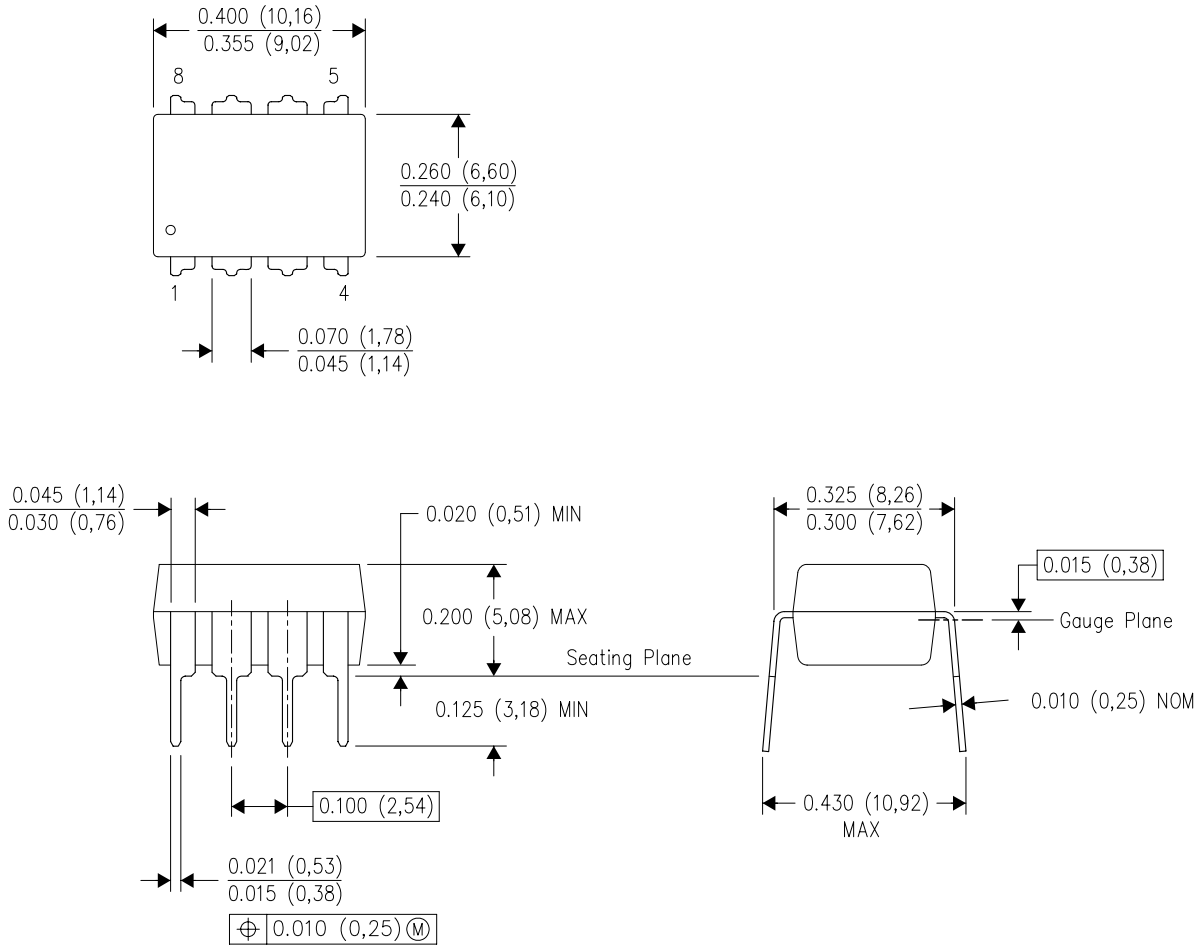
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

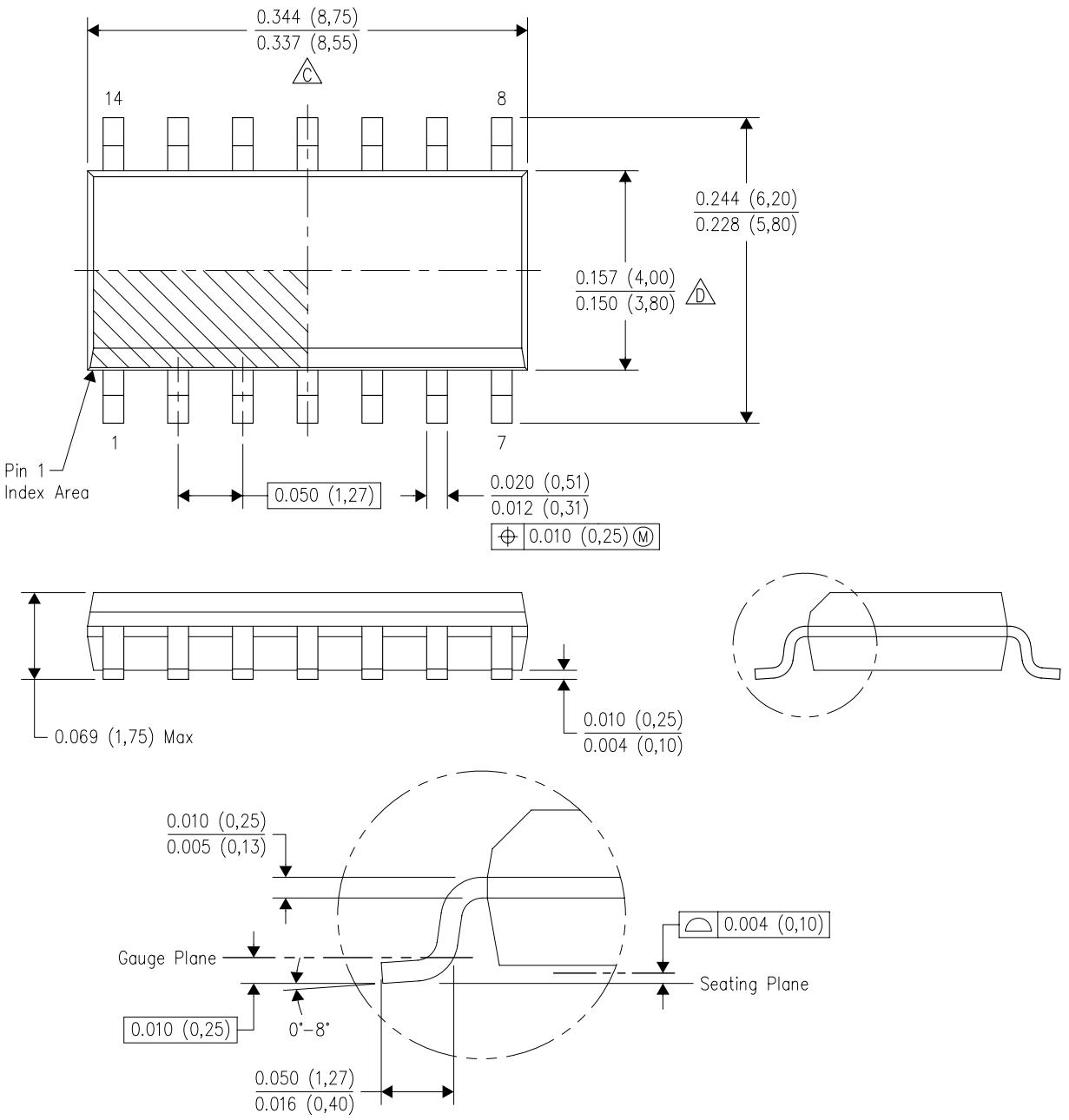
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2227U/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA2227UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA2228U/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA2228UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA227U/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA227UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA228UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA4227UA/2K5	SOIC	D	14	2500	367.0	367.0	38.0
OPA4228UA/2K5	SOIC	D	14	2500	367.0	367.0	38.0

P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE



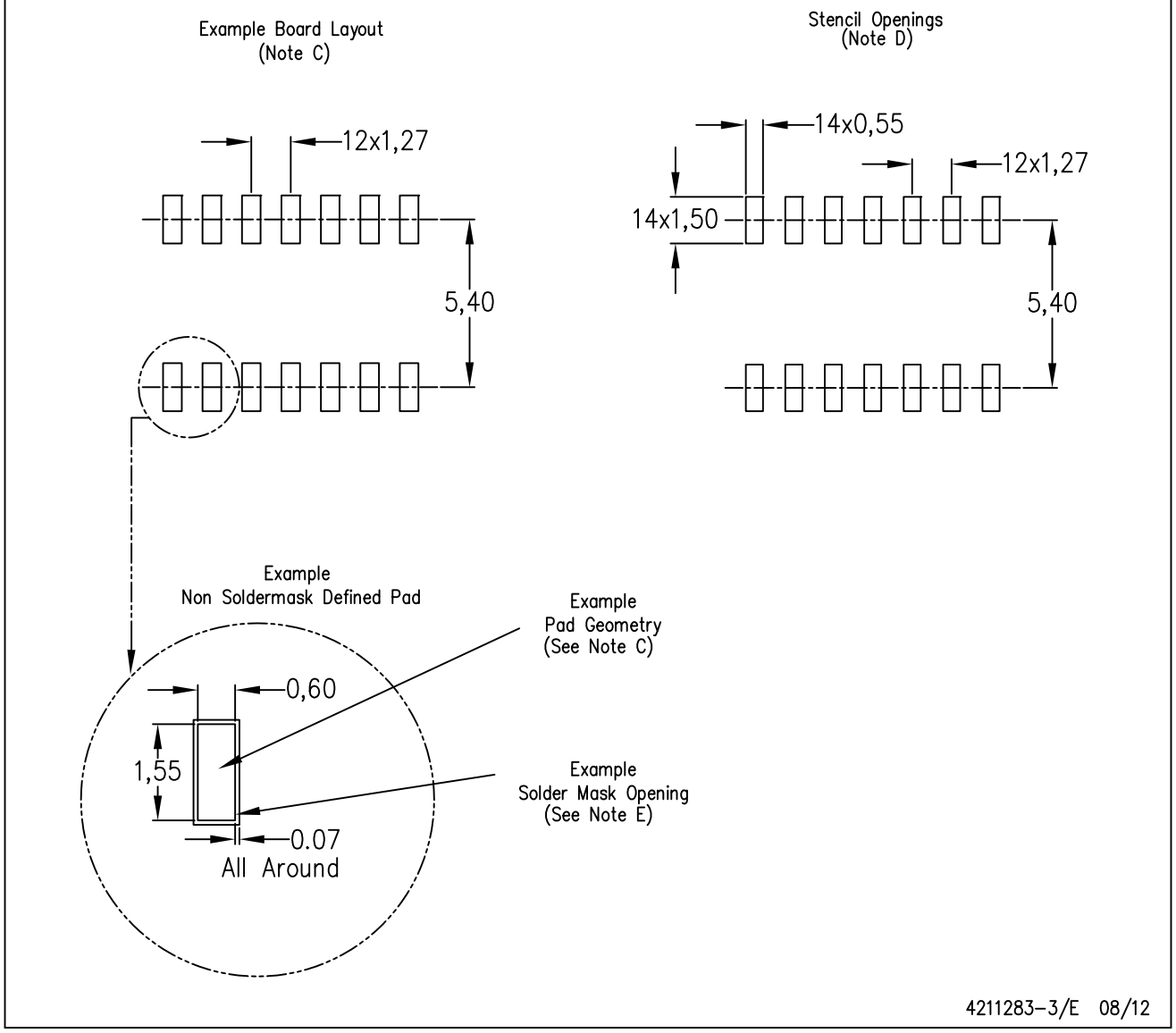
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001 variation BA.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE



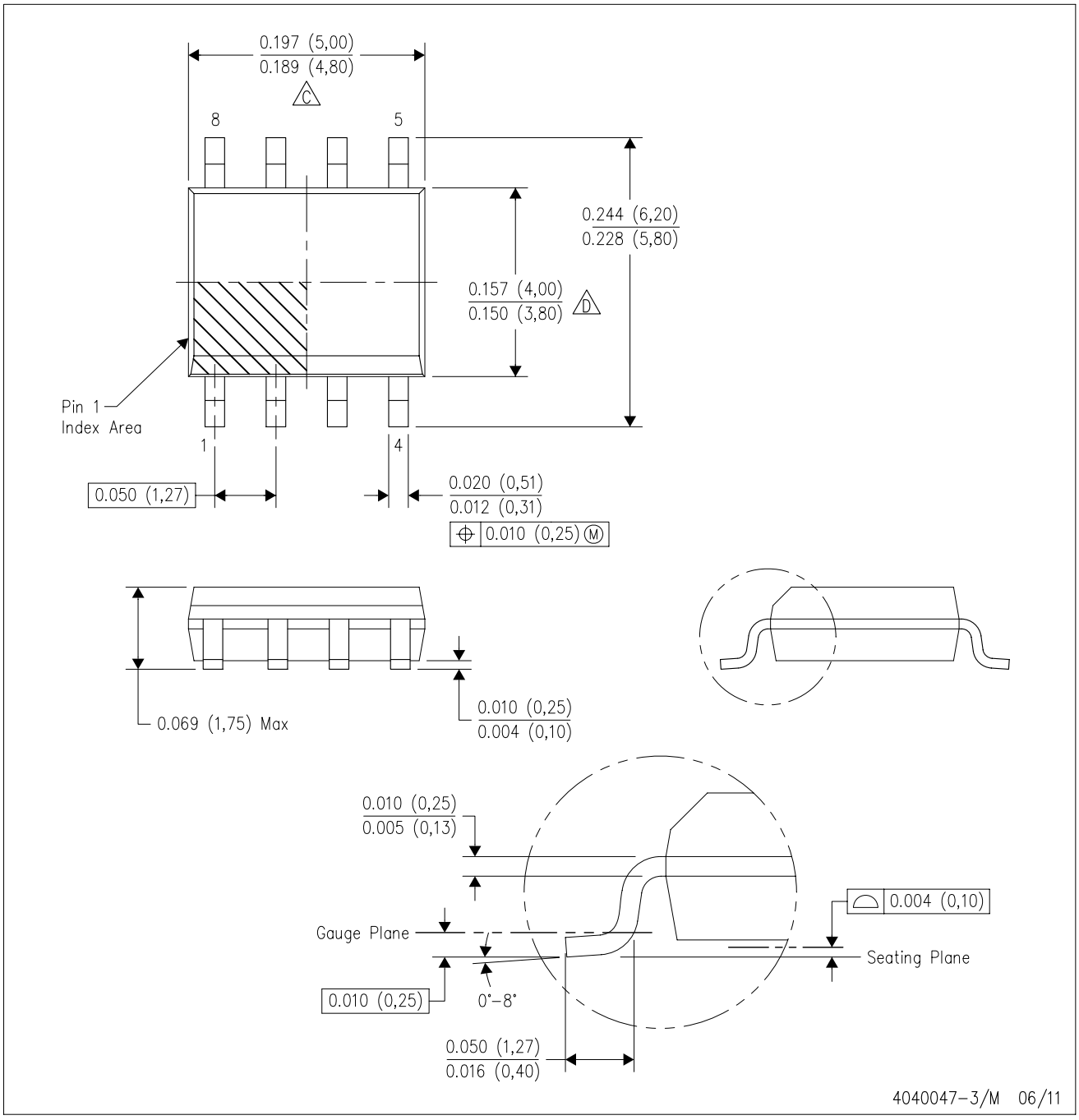
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AB.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE



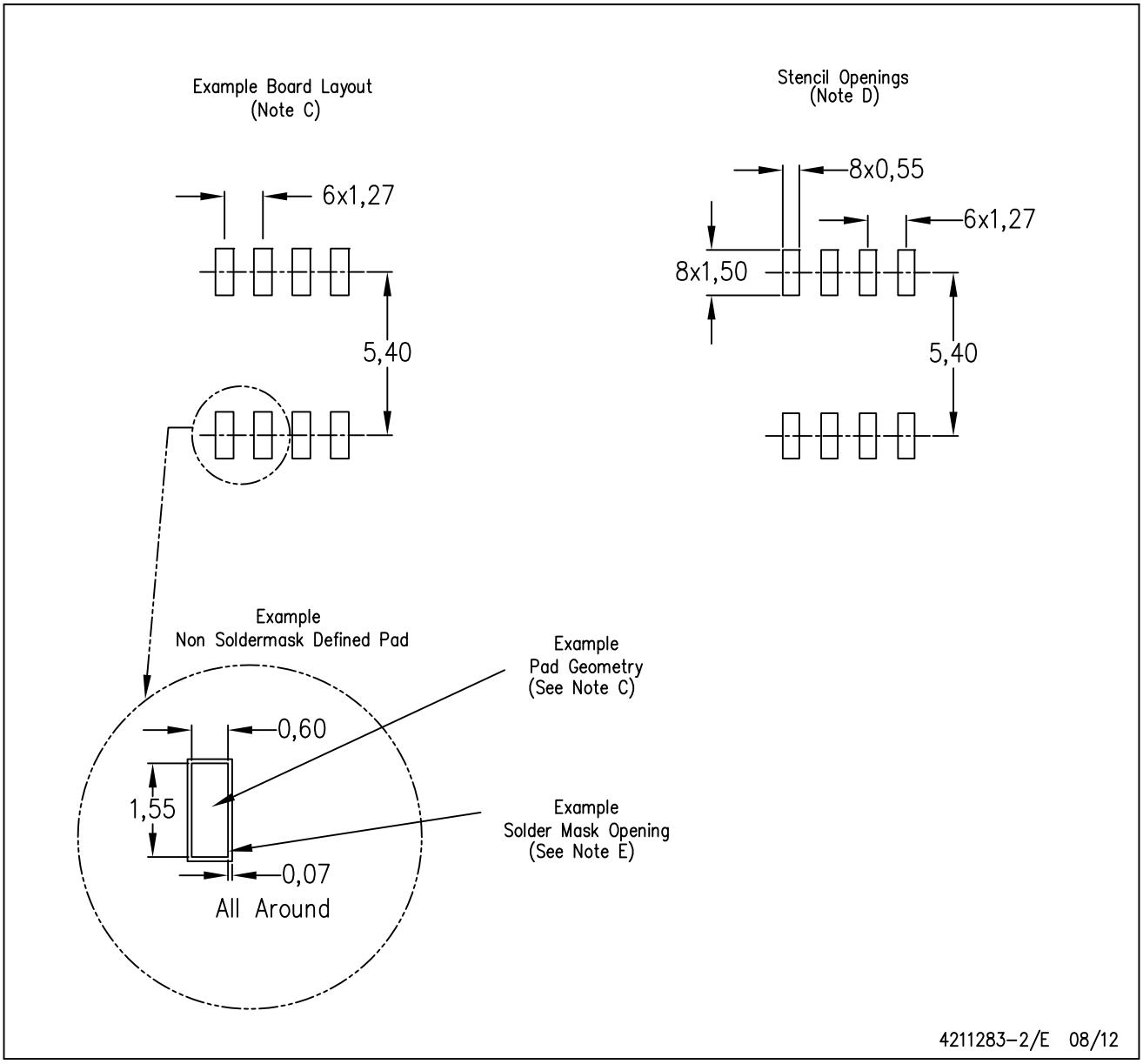
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AA.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2012, Texas Instruments Incorporated

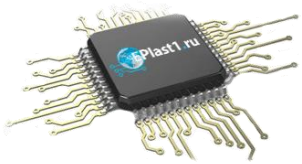
Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits,General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)
Факс: 8 (812) 320-02-42
Электронная почта: org@eplast1.ru
Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.